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APPLICATION NO.	F	ILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/833,953	09/833,953 04/11/2001		Marco Racanelli	00CON161P	3823
25700	7590	12/01/2004		EXAM	IINER
FARJAMI		AMI LLP A AVENUE, SUITE :	MALDONADO, JULIO J		
MISSION V		•	ART UNIT	PAPER NUMBER	
				2823	

DATE MAILED: 12/01/2004

Please find below and/or attached an Office communication concerning this application or proceeding.

		Application No.	Applicant(s)
Office Action Summary		09/833,953	RACANELLI, MARCO
		Examiner	Art Unit
		Julio J. Maldonado	2823
Period f	The MAILING DATE of this communication a or Reply	ppears on the cover sheet wi	th the correspondence address
A SH THE - Exte after - If th - If NO - Failt Any	IORTENED STATUTORY PERIOD FOR REP MAILING DATE OF THIS COMMUNICATION ensions of time may be available under the provisions of 37 CFR of SIX (6) MONTHS from the mailing date of this communication. The period for reply specified above is less than thirty (30) days, a report of the provision of the period for reply is specified above, the maximum statutory period reply within the set or extended period for reply will, by status reply received by the Office later than three months after the mained patent term adjustment. See 37 CFR 1.704(b).	I. 1.136(a). In no event, however, may a re eply within the statutory minimum of thirt od will apply and will expire SIX (6) MON ute, cause the application to become AB	eply be timely filed y (30) days will be considered timely. THS from the mailing date of this communication. ANDONED (35 U.S.C. § 133).
Status		•	
1)⊠ 2a)⊠ 3)□		nis action is non-final. vance except for formal matt	•
Disposit	ion of Claims		
5)□ 6)⊠ 7)□	Claim(s) <u>1,3-15,17-23 and 25</u> is/are pending 4a) Of the above claim(s) is/are withded Claim(s) is/are allowed. Claim(s) <u>1,3-15,17-23 and 25</u> is/are rejected Claim(s) is/are objected to. Claim(s) are subject to restriction and	rawn from consideration.	
Applicat	ion Papers		
10)	The specification is objected to by the Exami The drawing(s) filed on is/are: a) ac Applicant may not request that any objection to the Replacement drawing sheet(s) including the corre The oath or declaration is objected to by the	ccepted or b) objected to note on the drawing(s) be held in abeyant ection is required if the drawing(nce. See 37 CFR 1.85(a). (s) is objected to. See 37 CFR 1.121(d).
Priority	under 35 U.S.C. § 119		
a)	Acknowledgment is made of a claim for foreign All b) Some * c) None of: 1. Certified copies of the priority docume 2. Certified copies of the priority docume 3. Copies of the certified copies of the priority docume application from the International Bure See the attached detailed Office action for a li	ents have been received. ents have been received in A riority documents have been eau (PCT Rule 17.2(a)).	pplication No received in this National Stage
Attachmer	nt(s) ce of References Cited (PTO-892)	4) ☐ Interview S	Summary (PTO-413)
2)	ce of Draftsperson's Patent Drawing Review (PTO-948) rmation Disclosure Statement(s) (PTO-1449 or PTO/SB/0 er No(s)/Mail Date	Paper No(s	s)/Mail Date formal Patent Application (PTO-152)

DETAILED ACTION

Claim Rejections - 35 USC § 103

- 1. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:
 - (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1, 3-15, 17-23 and 25 are rejected under 35 U.S.C. 103(a) as being unpatentable over Zaccherini (U.S. 5,436,177) in view of Erdeljac et al. (U.S. 5,489,547) and Shao et al. (U.S. 6,156,602).

In reference to claim 1 and 14 Zaccherini (Fig.1-6) teaches an analogous method to form semiconductor device including polysilicon resistors and transistors including forming a layer (7) comprising polycrystalline silicon over a transistor gate region (4) and a field oxide region (5) on a substrate (2, 3); forming a doping barrier (10) above said polycrystalline silicon over said field oxide region (5); doping said layer over said transistor gate region with a dose of a first dopant (11), wherein said dose of said first dopant (11) is a dosage greater than required to result in said layer over said transistor gate region (4) having transistor gate electrical properties, wherein said first dopant (11) has a first conductivity type; removing said doping barrier (10); and doping said layer over said transistor gate region (4) and said field oxide region (5) with a second dopant (13) so as to form a high resistivity resistor in said layer (7) over said field oxide region (5), without affecting said transistor gate electrical properties, wherein said second

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dopant (13) has a second conductivity type and wherein said resistor and said gate transistor region (4) are formed in a doped epitaxial layer (3) (column 3, lines 1-53).

Zaccherini fails to teach wherein said transistor gate region being situated over a well and said field oxide region not being situated over said well. However, Erdeljac et al. (Figs.8-11) teach a method to form semiconductor devices including polysilicon resistors and transistors formed on a substrate (10, 12, 18), wherein said substrate (10, 12, 18) includes a well region (18) and wherein said method includes forming resistors (32, 34, 56) over a field oxide region (20); forming a transistor region (44), wherein said transistor region (44) and said resistors (32, 34, 56) are formed in a doped epitaxial layer (12); and further teach forming gate electrode regions (50) over a well (18), wherein said field oxide region (20) having said resistors (32, 34, 56) formed therein is located away from said well (18) (column 5, line 10 – column 6, line 21). It would have been within the scope of one of ordinary skill in the art to combine the teachings of Zaccherini and Erdeljac et al. to enable forming the gate transistors and field oxide regions of Zaccherini on the substrate of Erdeljac et al. because one of ordinary skill in the art at the time the invention was made would have been motivated to look to alternative suitable methods of forming the gate electrodes and the field oxide regions of Zaccherini and art recognized suitability for an intended purpose has been recognized to be motivation to combine. MPEP 2144.07.

The combined teachings of Zaccherini and Erdeljac et al. fail to teach wherein the resistor region of said polycrystalline silicon layer includes an inner portion and an outer portion and further comprises the steps of forming a silicide blocking layer in said

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inner portion of said resistor region; doping said outer portion of said resistor region of said polycrystalline silicon layer with a third dopant so as to form a high-doped region in said resistor region, wherein said third dopant has said second conductivity type; and fabricating a contact region over said high-doped region in said outer portion of said resistor region of said polycrystalline silicon layer, wherein said contact region being electrically connected to said resistor region. However, Shao et al. (Figs.1-7) in a related method to form implanted regions teach forming a layer (16) comprising polycrystalline silicon over a transistor gate region and a field oxide region (12); doping the field oxide region (12) having said polycrystalline silicon therein with a dopant of a first conductivity type, thus forming a resistor region (38); forming a transistor gate region (40) by patterning the polysilicon layer (16); and, in a separate doping step, forming a blocking oxide layer (60) in an inner portion of said resistor; doping an outer portion of said resistor region (38) of said polycrystalline silicon layer (16) with a dopant of said first conductivity type so as to form a high-doped region (72, 74) in said resistor region; and fabricating a contact region (column 8, lines 9 – 20) over said high-doped region (72, 74) in said resistor region (38) of said polycrystalline silicon layer (16), said contact region (72, 74) being electrically connected to said resistor region (38) (column 4, line 20 - column 8, line 42).

Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to combine the teachings of Zaccherini and Erdeljac et al. with the teachings of Shao et al. to enable forming high doping areas and electrical contacts in the high resistivity resistor of Zaccherini and Erdeljac et al., as taught by

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Shao et al., since this would result in the formation of electrical points of contact (column 8, lines 9 - 10).

In reference to claims 3-13, 15, 17-23 and 25, the combined teachings of Zaccherini, Erdeljac et al. and Shao et al. teach wherein said layer comprises polysilicon (Zaccherini, column 3, lines 1 – 6); wherein said transistor region is an NFET or an PFET (Shao et al., column 5, lines 7 – 21); wherein said field oxide region comprises silicon oxide (Zaccherini, column 2, lines 53 – 61); wherein the first dopant is an N-type dopant comprising phosphorous at a dose of approximately 1x10¹⁵ to 1x10¹⁶ atoms per square centimeter (Zaccherini, column 3, lines 23 – 32); wherein the second dopant is a P-type dopant comprising boron at a dose of approximately 1.0x10¹² to 1.0x10¹⁵ atoms per square centimeter (Zaccherini, column 3, lines 44 – 53); wherein said doping barrier comprises a photoresist (Zaccherini, Fig.4); wherein the polycrystalline silicon layer includes a gate region (4) (Zaccherini, column 2, lines 46 – 60); and wherein said contact region comprises a silicide (Shao et al., column 8, lines 8 – 20).

The combined teachings of Zaccherini, Erdeljac et al. and Shao et al. fail to expressly teach wherein said first dopant is doped at a dose of approximately 6.5 x 10¹⁵ atoms per square centimeter; and wherein said second dopant is doped at a dose of 1.0 x 10¹⁵ atoms per square centimeter. However, in the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. MPEP 2144.05. Therefore, it would have been obvious to one of ordinary skill in the art at the time the invention was made to use the disclosed dopant

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concentration disclosed in the combined teachings of Zaccherini, Erdeljac et al. and Shao et al. to arrive at the claimed invention.

Response to Arguments

- 3. Applicant's arguments filed 09/21/2004 have been fully considered but they are not persuasive.
- 4. In response to applicant's argument that there is no suggestion to combine the references, the examiner recognizes that obviousness can only be established by combining or modifying the teachings of the prior art to produce the claimed invention where there is some teaching, suggestion, or motivation to do so found either in the references themselves or in the knowledge generally available to one of ordinary skill in the art. See In re Fine, 837 F.2d 1071, 5 USPQ2d 1596 (Fed. Cir. 1988)and In re Jones, 958 F.2d 347, 21 USPQ2d 1941 (Fed. Cir. 1992). In this case, Zaccherini teaches a method of forming resistor and transistor by performing the doping process disclosed in the claimed invention on a substrate. Having this in mind, Erdeljac et al. teaches a method of forming transistor and resistor regions on a substrate that includes a well region. Furthermore, Shao et al. teach forming contacts on the resistor formed on the resistor region for the further advantage of in the formation of electrical points of contact (Shao et al., column 8, lines 9 – 10). Since there is knowledge prior in the art to form transistor regions in the same regions disclosed in the claimed invention and furthermore, since there is a further advantage of forming the claimed contacts on the claimed resistor regions prior in the art, the combination of the prior art of record is proper.

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5. Also, in response to applicant's arguments against the references individually,

one cannot show nonobviousness by attacking references individually where the

rejections are based on combinations of references. See In re Keller, 642 F.2d 413,

208 USPQ 871 (CCPA 1981); In re Merck & Co., 800 F.2d 1091, 231 USPQ 375 (Fed.

Cir. 1986).

Conclusion

6. Any inquiry of a general nature or relating to the status of this application should

be directed to the Group Receptionist whose telephone number is 571-272-2800. See

MPEP 203.08.

7. Any inquiry concerning this communication or earlier communications from the

examiner should be directed to examiner Julio J. Maldonado whose telephone number

is (571) 272-1864. The examiner can normally be reached on Monday through Friday.

8. If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Olik Chaudhuri, can be reached on (571) 272-1855. The fax number for this

group is 703-872-9306 for before final submissions, 703-872-9306 for after final

submissions and the customer service number for group 2800 is (703) 306-3329.

Updates can be found at http://www.uspto.gov/web/info/2800.htm.

Julio J. Maldonado Patent Examiner Art Unit 2823

Julio J. Maldonado June 9, 2004

George Fourson
Primary Examiner